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## **OPEN** Publisher Correction: Morphology and mechanics of fungal mycelium

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The original PDF version of this Article contained errors. Figures 3, 4 and 7 were duplicated in Figures 4, 6 and 10 respectively, Figures 4-8 were incorrectly listed as Figures 5, 7, 8, 9 and 11 respectively and Figures 9-11 were missing.

These errors have now been corrected in the PDF version of this Article: the HTML version was correct from the time of publication.

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